L Number	Hits	Search Text	DB	Time stamp
1	261	(thinning with (substrate wafer)) and ("grid" "waffle")	USPAT; US-PGPUB	2003/07/22 10:10
2	2624	(thinning with (substrate wafer))	USPAT; US-PGPUB	2003/07/22 10:10
3	22264	metal with mask	USPAT; US-PGPUB	2003/07/22 10:11
4	14	((thinning with (substrate wafer))) with (metal with mask)	USPAT; US-PGPUB	2003/07/22 10:11
-	1752	((43/460) or (438/463) or (438/606) or (438/107) or (438/620) or (438/712) or (438/718) or (438/728) or (438/733) or (738/742)).CCLS.	USPAT; US-PGPUB	2003/07/21 08:55
-	11	(((43/460) or (438/463) or (438/606) or (438/107) or (438/620) or (438/712) or (438/718) or (438/728) or (438/733) or (738/742)).CCLS.) and (thinning with (substrate wafer)) and ("grid" "waffle")	USPAT; US-PGPUB	2003/07/21 09:50
-	260	(thinning with (substrate wafer)) and ("grid" "waffle")	USPAT; US-PGPUB	2003/07/22 10:09
-	11	("5096854" | "5213657" | "5840614" | "5891298" | "5968849" | "5981391" | "6017822" | "6020252" | "6033995" | "6046117" | "6100166").PN.	USPAT	2003/07/21 09:48
-	0	6162702.URPN.	USPAT	2003/07/21 09:49
-	2618	(thinning with (substrate wafer))	USPAT; US-PGPUB	2003/07/21 09:51
-	15144	radio with frequency with circuit	USPAT; US-PGPUB	2003/07/21 09:51
-	0	((thinning with (substrate wafer))) with (radio with frequency with circuit)	USPAT; US-PGPUB	2003/07/21 09:52
-	27	((thinning with (substrate wafer))) and (radio with frequency with circuit)	USPAT; US-PGPUB	2003/07/21 09:52
-	7	5336930.URPN.	USPAT	2003/07/21 10:02
-	13	5221221.URPN.	USPAT	2003/07/21 10:19
-	7	5336930.URPN.	USPAT	2003/07/21 10:20
-	9	("3648131" | "4447291" | "4507674" | "4789645" | "4849376" | "4965218" | "4970578" | "4972250" | "4977100").PN.	USPAT	2003/07/21 10:21
-	10	4970578.URPN.	USPAT	2003/07/21 10:22
-	10	4970578.URPN.	USPAT	2003/07/21 10:29
-	14	("3986196" | "4091408" | "4374394" | "4376287" | "4571611" | "4601096" | "4751562" | "4794093" | "4807022" | "4818724" | "4823174" | "4827610" | "4868613" | "4896194").PN.	USPAT	2003/07/21 10:30
-	12	4868613.URPN.	USPAT	2003/07/21 10:32
-	12	5064772.URPN.	USPAT	2003/07/21 10:35
-	0	mmic with thining with (substrate wafer)	USPAT; US-PGPUB	2003/07/21 10:35
-	0	mmic and (thining with (substrate wafer))	USPAT; US-PGPUB	2003/07/21 10:36
-	7	(thining with (substrate wafer))	USPAT; US-PGPUB	2003/07/21 10:37
-	2618	(thinning with (substrate wafer))	USPAT; US-PGPUB	2003/07/22 10:10
-	29	((thinning with (substrate wafer))) and mmic	USPAT; US-PGPUB	2003/07/21 10:38
-	0	10034723.pn.	USPAT; US-PGPUB	2003/07/21 11:38
-	0	"10034723"	USPAT; US-PGPUB	2003/07/21 11:41
-	0	((thinning with (substrate wafer))) and vernier with marker	USPAT; US-PGPUB	2003/07/21 11:41
-	48	vernier with marker	USPAT; US-PGPUB	2003/07/21 11:48
-	438	438/462.ccls.	USPAT; US-PGPUB	2003/07/21 11:49
-	41	438/462.ccls. and thinning with (substrate wafer)	USPAT; US-PGPUB	2003/07/21 11:51

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-	0	438/462.ccls. and mmisc	USPAT; US-PGPUB	2003/07/21 11:51
-	7	438/462.ccls. and mmic	USPAT; US-PGPUB	2003/07/21 11:52
-	29	438/462.ccls. and depth with mark	USPAT; US-PGPUB	2003/07/21 12:03
-	2	438/462.ccls. and backside and (depth with mark)	USPAT; US-PGPUB	2003/07/21 12:04
-	12	438/462.ccls. and backside and ((alignment depth) with mark)	USPAT; US-PGPUB	2003/07/21 13:03
-	0	"09034747"	USPAT; US-PGPUB	2003/07/21 13:05
-	0	"10034747"	USPAT; US-PGPUB	2003/07/21 13:05
-	2	measured with via with etch with etching	USPAT; US-PGPUB	2003/07/21 13:05
-	0	(measured with via with hole with etching) and bernier	USPAT; US-PGPUB	2003/07/21 13:06
-	0	(measured with via with hole with etching) and vernier	USPAT; US-PGPUB	2003/07/21 13:06
-	6	measured with via with hole with etching	USPAT; US-PGPUB	2003/07/21 13:06
-	1945	hemt	USPAT; US-PGPUB	2003/07/22 08:50
-	382	hemt and mmic	USPAT; US-PGPUB	2003/07/22 08:50
-	117	(hemt and mmic) and pad	USPAT; US-PGPUB	2003/07/22 08:50
-	0	((hemt and mmic) and pad) and thinning with (substrate wafer)	USPAT; US-PGPUB	2003/07/22 08:57
-	37	((hemt and mmic) and pad) and (thin thins thinning) with (substrate wafer)	USPAT; US-PGPUB	2003/07/22 08:59
-	87	(hemt and mmic) and mmic and ((source and drain) with region)	USPAT; US-PGPUB	2003/07/22 09:01
-	21	((hemt and mmic) and mmic and ((source and drain) with region)) and ((source and drain) with pad)	USPAT; US-PGPUB	2003/07/22 09:01

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